IN THE SPECIFICATION:

On page 9 of the specification, please amend the description of Fig. 1, as follows:

~~FIG. 1~~ FIGs. 1A-1D ~~is an illustration~~ are illustrations showing a first embodiment of the present invention;

On page 11 please amend the paragraph beginning on line 8 and ending on line 14 as follows:

~~Fig. 1 illustrates~~ Figs. 1A-1D illustrate an ILS with an embodiment of the present invention. A via is created in the ILS through the stainless steel layer 212 at 204, the polymide layer 210 at 202, and the copper layer 208 at 200 that exposes the arm surface. A drop of conductive adhesive is placed in the via to connect the stainless steel layer through the polymide layer to the copper layer and the arm surface.

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently amended) A method of creating a conductive path between two or more conductive layers, wherein the conductive layers are separated by one or more dielectric layers, the method comprising:

applying a conductive material to exposed portions of at least two conductive layers, the conductive material creating an electrical coupling between the conductive layers; and

grounding at least one of the conductive layers to a controlled ground potential;

wherein the portions of the conductive layers are exposed by recessing an edge of at least one of the conductive layers and any dielectric layers positioned between the conductive layers to form stepped back edges on

the one of the conductive layers and the one or more dielectric layers, the conductive material overhanging an uppermost of the conductive layers.

2. (Cancelled)

3. (Previously presented) The method as recited in claim 1, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

4. (Previously presented) The method as recited in claim 1, wherein the conductive material is a conductive adhesive.

5. (Currently Amended) The method as recited in claim 1, wherein one or more of the conductive layers is grounded to a the controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

6. (Cancelled)

7. (Cancelled)

8. (Cancelled)

9. (Previously presented) The method as recited in claim 1, wherein the conductive material is plated solder.

10. (Previously presented) The method as recited in claim 1, wherein the conductive material is screen solder.

11. (Previously presented) The method as recited in claim 1, wherein the conductive material is solder, and further comprising reflowing the solder.

12. (Cancelled)

13. (Cancelled)

14. (Previously presented) The method as recited in claim 1, further comprising exposing the exposed portions of the at least one conductive layer.

15. (Previously presented) The method as recited in claim 1, wherein the conductive layers form part of a lead suspension for suspending an electronic component.

16. (Previously presented) The method as recited in claim 15, wherein the electronic component is a magnetic head.

17. (Withdrawn) A method as recited in claim 14, wherein the finger is welded in place.

18. (Withdrawn) A method as recited in claim 1, wherein the conductive material is a finger formed by etching, the finger being sandwiched between a mount plate and a load beam.

19. (Withdrawn) A method as recited in claim 18, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel

20. (Withdrawn) A method as recited in claim 18, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

21. (Withdrawn) A method as recited in claim 18, wherein the finger is welded in place.

22. (Withdrawn) A method as recited in claim 1, further comprising an extraneous conductive layer, the conductive material being a dimple extending from the extraneous conducive layer and contacting the exposed portions of the conductive layers.

23. (Withdrawn) A method as recited in claim 22, wherein the dimple extends through a via in at least one of the conductive layers.

24. (Withdrawn) A method as recited in claim 22, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layer is stainless steel.

25. (Withdrawn) A method as recited in claim 22, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

26. (Withdrawn) A method as recited in claim 1, wherein the portions of the conductive layers are exposed by punching a hole through the conductive layers, the conductive material extending through the hole.

27. (Withdrawn) A method as recited in claim 26, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

28. (Withdrawn) A method as recited in claim 26, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.